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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Obsolete
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	80MHz
Connectivity	I ² C, IrDA, LINbus, PMP, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	85
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	64K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 28x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	124-VFTLA Dual Rows, Exposed Pad
Supplier Device Package	124-VTLA (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx450f256lt-i-tl

PIC32MX330/350/370/430/450/470

TABLE 7: PIN NAMES FOR 124-PIN DEVICES (CONTINUED)

124-PIN VTLA (BOTTOM VIEW)^(1,2,3,4) PIC32MX430F064L PIC32MX450F128L PIC32MX450F256L PIC32MX470F512L		A17	B13	B29	A34	Conductive Thermal Pad
			B1	B56	B41	A51
		A1				
		Polarity Indicator		A68		
Package Bump #	Full Pin Name		Package Bump #	Full Pin Name		
B7	MCLR		B32	SDA2/RA3		
B8	Vss		B33	TDO/RA5		
B9	TMS/CTED1/RA0		B34	OSC1/CLK1/RC12		
B10	RPE9/RE9		B35	No Connect		
B11	AN4/C1INB/RB4		B36	SCL1/RPA14/RA14		
B12	Vss		B37	RPD8/RTCC/RD8		
B13	PGEC3/AN2/C2INB/RPB2/CTED13/RB2		B38	RPD10/SCK1/PMCS2/RD10		
B14	PGED1/AN0/RPB0/RB0		B39	RPD0/INT0/RD0		
B15	No Connect		B40	SOSCO/RPC14/T1CK/RC14		
B16	PGED2/AN7/RPB7/CTED3/RB7		B41	Vss		
B17	VREF+/CVREF+/PMA6/RA10		B42	AN25/RPD2/RD2		
B18	AVss		B43	RPD12/PMD12/RD12		
B19	AN9/RPB9/CTED4/RB9		B44	RPD4/PMWR/RD4		
B20	AN11/PMA12/RB11		B45	PMD14/RD6		
B21	VDD		B46	No Connect		
B22	RPF13/RF13		B47	No Connect		
B23	AN12/PMA11/RB12		B48	VCAP		
B24	AN14/RPB14/CTED5/PMA1/RB14		B49	RPF0/PMD11/RF0		
B25	Vss		B50	RPG1/PMD9/RG1		
B26	RPD14/RD14		B51	TRCLK/RA6		
B27	RPF4/PMA9/RF4		B52	PMD0/RE0		
B28	No Connect		B53	VDD		
B29	RPF8/RF8		B54	TRD2/RG14		
B30	VUSB3v3		B55	TRD0/RG13		
B31	D+		B56	RPE3/CTPLS/PMD3/RE3		

- Note** 1: The RPN pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 12.3 “Peripheral Pin Select”** for restrictions.
- 2: Every I/O port pin (RAX-RGX) can be used as a change notification pin (CNAX-CNGX). See **Section 12.0 “I/O Ports”** for more information.
- 3: Shaded package bumps are 5V tolerant.
- 4: It is recommended that the user connect the printed circuit board (PCB) ground to the conductive thermal pad on the bottom of the package. And to not run non-Vss PCB traces under the conductive thermal pad on the same side of the PCB layout.

2.5 ICSP Pins

The PGECx and PGEDx pins are used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin input voltage high (V_{IH}) and input low (V_{IL}) requirements.

Ensure that the “Communication Channel Select” (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB® ICD 3 or MPLAB REAL ICE™.

For more information on ICD 3 and REAL ICE connection requirements, refer to the following documents that are available on the Microchip web site.

- “Using MPLAB® ICD 3” (poster) DS50001765
- “MPLAB® ICD 3 Design Advisory” DS50001764
- “MPLAB® REAL ICE™ In-Circuit Debugger User’s Guide” DS50001616
- “Using MPLAB® REAL ICE™ Emulator” (poster) DS50001749

2.6 JTAG

The TMS, TDO, TDI and TCK pins are used for testing and debugging according to the Joint Test Action Group (JTAG) standard. It is recommended to keep the trace length between the JTAG connector and the JTAG pins on the device as short as possible. If the JTAG connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes and capacitors on the TMS, TDO, TDI and TCK pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin input voltage high (V_{IH}) and input low (V_{IL}) requirements.

2.7 Trace

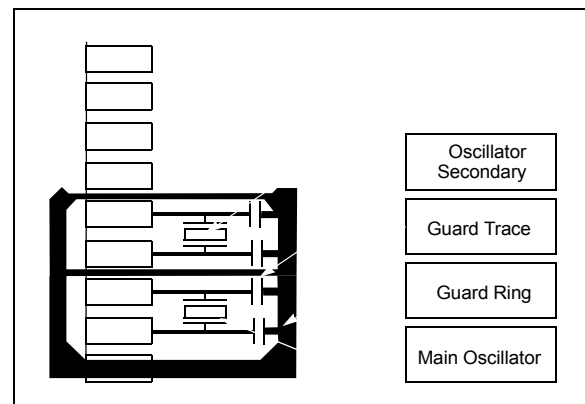
The trace pins can be connected to a hardware trace-enabled programmer to provide a compressed real-time instruction trace. When used for trace, the TRD3, TRD2, TRD1, TRD0 and TRCLK pins should be dedicated for this use. The trace hardware requires a 22 Ohm series resistor between the trace pins and the trace connector.

2.8 External Oscillator Pins

Many MCUs have options for at least two oscillators: a high-frequency primary oscillator and a low-frequency secondary oscillator (refer to **Section 8.0 “Oscillator Configuration”** for details).

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator itself, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed. A suggested layout is illustrated in Figure 2-3.

FIGURE 2-3: SUGGESTED OSCILLATOR CIRCUIT PLACEMENT



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REGISTER 7-6: IPCx: INTERRUPT PRIORITY CONTROL REGISTER (CONTINUED)

- bit 9-8 **IS1<1:0>**: Interrupt Subpriority bits
11 = Interrupt subpriority is 3
10 = Interrupt subpriority is 2
01 = Interrupt subpriority is 1
00 = Interrupt subpriority is 0
- bit 7-5 **Unimplemented**: Read as '0'
- bit 4-2 **IP0<2:0>**: Interrupt Priority bits
111 = Interrupt priority is 7
.
.
.
010 = Interrupt priority is 2
001 = Interrupt priority is 1
000 = Interrupt is disabled
- bit 1-0 **IS0<1:0>**: Interrupt Subpriority bits
11 = Interrupt subpriority is 3
10 = Interrupt subpriority is 2
01 = Interrupt subpriority is 1
00 = Interrupt subpriority is 0

Note: This register represents a generic definition of the IPCx register. Refer to Table 7-1 for the exact bit definitions.
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REGISTER 10-7: DCHxCON: DMA CHANNEL 'x' CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
	CHBUSY	—	—	—	—	—	—	CHCHNS ⁽¹⁾
7:0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	R-0	R/W-0	R/W-0
	CHEN ⁽²⁾	CHAED	CHCHN	CHAEN	—	CHEDET	CHPRI<1:0>	

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **CHBUSY:** Channel Busy bit

1 = Channel is active or has been enabled

0 = Channel is inactive or has been disabled

bit 14-9 **Unimplemented:** Read as '0'

bit 8 **CHCHNS:** Chain Channel Selection bit⁽¹⁾

1 = Chain to channel lower in natural priority (CH1 will be enabled by CH2 transfer complete)

0 = Chain to channel higher in natural priority (CH1 will be enabled by CH0 transfer complete)

bit 7 **CHEN:** Channel Enable bit⁽²⁾

1 = Channel is enabled

0 = Channel is disabled

bit 6 **CHAED:** Channel Allow Events If Disabled bit

1 = Channel start/abort events will be registered, even if the channel is disabled

0 = Channel start/abort events will be ignored if the channel is disabled

bit **CHCHN:** Channel Chain Enable bit

1 = Allow channel to be chained

0 = Do not allow channel to be chained

bit 4 **CHAEN:** Channel Automatic Enable bit

1 = Channel is continuously enabled, and not automatically disabled after a block transfer is complete

0 = Channel is disabled on block transfer complete

bit 3 **Unimplemented:** Read as '0'

bit 2 **CHEDET:** Channel Event Detected bit

1 = An event has been detected

0 = No events have been detected

bit 1-0 **CHPRI<1:0>:** Channel Priority bits

11 = Channel has priority 3 (highest)

10 = Channel has priority 2

01 = Channel has priority 1

00 = Channel has priority 0

Note 1: The chain selection bit takes effect when chaining is enabled (i.e., CHCHN = 1).

2: When the channel is suspended by clearing this bit, the user application should poll the CHBUSY bit (if available on the device variant) to see when the channel is suspended, as it may take some clock cycles to complete a current transaction before the channel is suspended.

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REGISTER 10-9: DCHxINT: DMA CHANNEL 'x' INTERRUPT CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHSDIE	CHSHIE	CHDDIE	CHDHIE	CHBCIE	CHCCIE	CHTAIE	CHERIE
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHSDIF	CHSHIF	CHDDIF	CHDHIF	CHBCIF	CHCCIF	CHTAIF	CHERIF

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 31-24 **Unimplemented:** Read as '0'

bit 23 **CHSDIE:** Channel Source Done Interrupt Enable bit

1 = Interrupt is enabled

0 = Interrupt is disabled

bit 22 **CHSHIE:** Channel Source Half Empty Interrupt Enable bit

1 = Interrupt is enabled

0 = Interrupt is disabled

bit 21 **CHDDIE:** Channel Destination Done Interrupt Enable bit

1 = Interrupt is enabled

0 = Interrupt is disabled

bit 20 **CHDHIE:** Channel Destination Half Full Interrupt Enable bit

1 = Interrupt is enabled

0 = Interrupt is disabled

bit 19 **CHBCIE:** Channel Block Transfer Complete Interrupt Enable bit

1 = Interrupt is enabled

0 = Interrupt is disabled

bit 18 **CHCCIE:** Channel Cell Transfer Complete Interrupt Enable bit

1 = Interrupt is enabled

0 = Interrupt is disabled

bit 17 **CHTAIE:** Channel Transfer Abort Interrupt Enable bit

1 = Interrupt is enabled

0 = Interrupt is disabled

bit 16 **CHERIE:** Channel Address Error Interrupt Enable bit

1 = Interrupt is enabled

0 = Interrupt is disabled

bit 15-8 **Unimplemented:** Read as '0'

bit 7 **CHSDIF:** Channel Source Done Interrupt Flag bit

1 = Channel Source Pointer has reached end of source (CHSPTR = CHSSIZ)

0 = No interrupt is pending

bit 6 **CHSHIF:** Channel Source Half Empty Interrupt Flag bit

1 = Channel Source Pointer has reached midpoint of source (CHSPTR = CHSSIZ/2)

0 = No interrupt is pending

bit 5 **CHDDIF:** Channel Destination Done Interrupt Flag bit

1 = Channel Destination Pointer has reached end of destination (CHDPTR = CHDSIZ)

0 = No interrupt is pending

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REGISTER 18-3: SPIxSTAT: SPI STATUS REGISTER (CONTINUED)

- bit 3 **SPITBE:** SPI Transmit Buffer Empty Status bit
1 = Transmit buffer, SPIxTXB is empty
0 = Transmit buffer, SPIxTXB is not empty
Automatically set in hardware when SPI transfers data from SPIxTXB to SPIxSR.
Automatically cleared in hardware when SPIxBUF is written to, loading SPIxTXB.
- bit 2 **Unimplemented:** Read as '0'
- bit 1 **SPITBF:** SPI Transmit Buffer Full Status bit
1 = Transmit not yet started, SPITXB is full
0 = Transmit buffer is not full
Standard Buffer Mode:
Automatically set in hardware when the core writes to the SPIBUF location, loading SPITXB.
Automatically cleared in hardware when the SPI module transfers data from SPITXB to SPIxSR.
Enhanced Buffer Mode:
Set when CWPTR + 1 = SRPTR; cleared otherwise
- bit 0 **SPIRBF:** SPI Receive Buffer Full Status bit
1 = Receive buffer, SPIxRXB is full
0 = Receive buffer, SPIxRXB is not full
Standard Buffer Mode:
Automatically set in hardware when the SPI module transfers data from SPIxSR to SPIxRXB.
Automatically cleared in hardware when SPIxBUF is read from, reading SPIxRXB.
Enhanced Buffer Mode:
Set when SWPTR + 1 = CRPTR; cleared otherwise

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REGISTER 19-2: I2CxSTAT: I²C STATUS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0 —	U-0 —	U-0 —	U-0 —	U-0 —	U-0 —	U-0 —	U-0 —
23:16	U-0 —	U-0 —	U-0 —	U-0 —	U-0 —	U-0 —	U-0 —	U-0 —
15:8	R-0, HSC ACKSTAT	R-0, HSC TRSTAT	U-0 —	U-0 —	U-0 —	R/C-0, HS BCL	R-0, HSC GCSTAT	R-0, HSC ADD10
7:0	R/C-0, HS IWCOL	R/C-0, HS I2COV	R-0, HSC D_A	R/C-0, HSC P	R/C-0, HSC S	R-0, HSC R_W	R-0, HSC RBF	R-0, HSC TBF

Legend:	HS = Set in hardware	HSC = Hardware set/cleared
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared
		C = Clearable bit

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **ACKSTAT:** Acknowledge Status bit
(when operating as I²C master, applicable to master transmit operation)
1 = Acknowledge was not received from slave
0 = Acknowledge was received from slave
Hardware set or clear at end of slave Acknowledge.

bit 14 **TRSTAT:** Transmit Status bit (when operating as I²C master, applicable to master transmit operation)
1 = Master transmit is in progress (8 bits + ACK)
0 = Master transmit is not in progress
Hardware set at beginning of master transmission. Hardware clear at end of slave Acknowledge.

bit 13-11 **Unimplemented:** Read as '0'

bit 10 **BCL:** Master Bus Collision Detect bit
1 = A bus collision has been detected during a master operation
0 = No collision
Hardware set at detection of bus collision. This condition can only be cleared by disabling (ON bit = 0) and re-enabling (ON bit = 1) the module.

bit 9 **GCSTAT:** General Call Status bit
1 = General call address was received
0 = General call address was not received
Hardware set when address matches general call address. Hardware clear at Stop detection.

bit 8 **ADD10:** 10-bit Address Status bit
1 = 10-bit address was matched
0 = 10-bit address was not matched
Hardware set at match of 2nd byte of matched 10-bit address. Hardware clear at Stop detection.

bit 7 **IWCOL:** Write Collision Detect bit
1 = An attempt to write the I2CxTRN register failed because the I²C module is busy
0 = No collision
Hardware set at occurrence of write to I2CxTRN while busy (cleared by software).

bit 6 **I2COV:** Receive Overflow Flag bit
1 = A byte was received while the I2CxRCV register is still holding the previous byte
0 = No overflow
Hardware set at attempt to transfer I2CxRSR to I2CxRCV (cleared by software).

bit 5 **D_A:** Data/Address bit (when operating as I²C slave)
1 = Indicates that the last byte received was data
0 = Indicates that the last byte received was device address
Hardware clear at device address match. Hardware set by reception of slave byte.

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NOTES:

23.0 10-BIT ANALOG-TO-DIGITAL CONVERTER (ADC)

Note: This data sheet summarizes the features of the PIC32MX330/350/370/430/450/470 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 17. “10-bit Analog-to-Digital Converter (ADC)”** (DS60001104), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The 10-bit Analog-to-Digital Converter (ADC) includes the following features:

- Successive Approximation Register (SAR) conversion
- Up to 1 Msps conversion speed
- Up to 28 analog input pins
- External voltage reference input pins
- One unipolar, differential Sample and Hold Amplifier (SHA)
- Automatic Channel Scan mode
- Selectable conversion trigger source
- 16-word conversion result buffer
- Selectable buffer fill modes
- Eight conversion result format options
- Operation during CPU Sleep and Idle modes

A block diagram of the 10-bit ADC is illustrated in Figure 23-1. The 10-bit ADC has up to 28 analog input pins, designated AN0-AN27. In addition, there are two analog input pins for external voltage reference connections. These voltage reference inputs may be shared with other analog input pins and may be common to other analog module references.

FIGURE 23-1: ADC1 MODULE BLOCK DIAGRAM

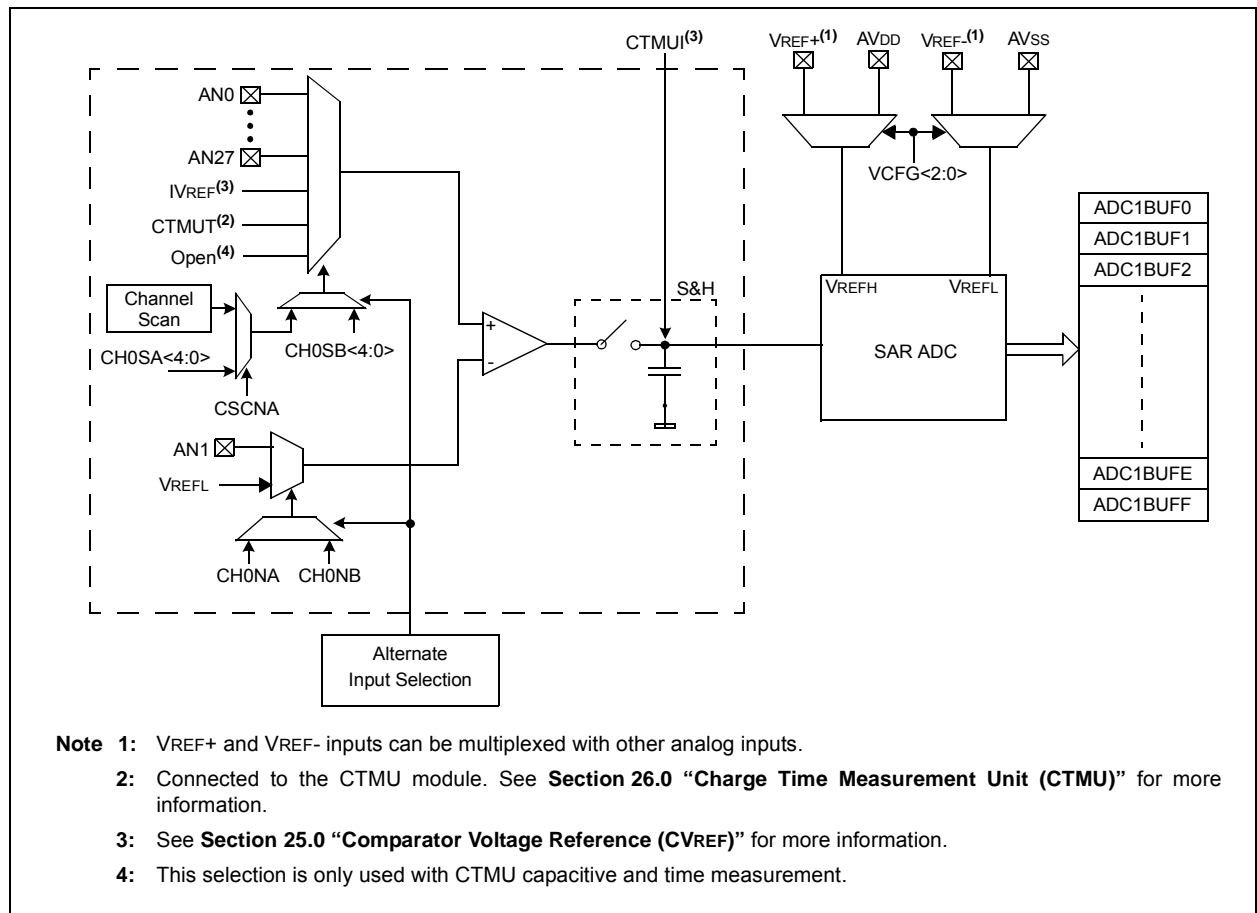


TABLE 23-1: ADC REGISTER MAP (CONTINUED)

Virtual Address (BF80_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
9110	ADC1BUFA	31:16	ADC Result Word A (ADC1BUFA<31:0>)																0000
		15:0																	0000
9120	ADC1BUFB	31:16	ADC Result Word B (ADC1BUFB<31:0>)																0000
		15:0																	0000
9130	ADC1BUFC	31:16	ADC Result Word C (ADC1BUFC<31:0>)																0000
		15:0																	0000
9140	ADC1BUFD	31:16	ADC Result Word D (ADC1BUFD<31:0>)																0000
		15:0																	0000
9150	ADC1BUFE	31:16	ADC Result Word E (ADC1BUFE<31:0>)																0000
		15:0																	0000
9160	ADC1BUFF	31:16	ADC Result Word F (ADC1BUFF<31:0>)																0000
		15:0																	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.2 “CLR, SET, and INV Registers”** for details.

REGISTER 26-1: CTMUCON: CTMU CONTROL REGISTER (CONTINUED)

- bit 10 **EDGSEQEN**: Edge Sequence Enable bit
 1 = Edge 1 must occur before Edge 2 can occur
 0 = No edge sequence is needed
- bit 9 **IDISSEN**: Analog Current Source Control bit⁽²⁾
 1 = Analog current source output is grounded
 0 = Analog current source output is not grounded
- bit 8 **CTTRIG**: Trigger Control bit
 1 = Trigger output is enabled
 0 = Trigger output is disabled
- bit 7-2 **ITRIM<5:0>**: Current Source Trim bits
 011111 = Maximum positive change from nominal current
 011110
 .
 .
 .
 000001 = Minimum positive change from nominal current
 000000 = Nominal current output specified by IRNG<1:0>
 111111 = Minimum negative change from nominal current
 .
 .
 .
 100010
 100001 = Maximum negative change from nominal current
- bit 1-0 **IRNG<1:0>**: Current Range Select bits⁽³⁾
 11 = 100 times base current
 10 = 10 times base current
 01 = Base current level
 00 = 1000 times base current⁽⁴⁾

- Note 1:** When this bit is set for Pulse Delay Generation, the EDG2SEL<3:0> bits must be set to '1110' to select C2OUT.
- 2:** The ADC module Sample and Hold capacitor is not automatically discharged between sample/conversion cycles. Software using the ADC as part of a capacitive measurement, must discharge the ADC capacitor before conducting the measurement. The IDISSEN bit, when set to '1', performs this function. The ADC module must be sampling while the IDISSEN bit is active to connect the discharge sink to the capacitor array.
- 3:** Refer to the CTMU Current Source Specifications (Table 31-42) in **Section 31.0 "Electrical Characteristics"** for current values.
- 4:** This bit setting is not available for the CTMU temperature diode.

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27.4.1 CONTROLLING CONFIGURATION CHANGES

Because peripherals can be disabled during run time, some restrictions on disabling peripherals are needed to prevent accidental configuration changes. PIC32 devices include two features to prevent alterations to enabled or disabled peripherals:

- Control register lock sequence
- Configuration bit select lock

27.4.1.1 Control Register Lock

Under normal operation, writes to the PMDx registers are not allowed. Attempted writes appear to execute normally, but the contents of the registers remain unchanged. To change these registers, they must be unlocked in hardware. The register lock is controlled by the PMDLOCK Configuration bit (CFGCON<12>). Setting PMDLOCK prevents writes to the control registers; clearing PMDLOCK allows writes.

To set or clear PMDLOCK, an unlock sequence must be executed. Refer to **Section 6. “Oscillator”** (DS60001112) in the *“PIC32 Family Reference Manual”* for details.

27.4.1.2 Configuration Bit Select Lock

As an additional level of safety, the device can be configured to prevent more than one write session to the PMDx registers. The PMDL1WAY Configuration bit (DEVCFG3<28>) blocks the PMDLOCK bit from being cleared after it has been set once. If PMDLOCK remains set, the register unlock procedure does not execute, and the peripheral pin select control registers cannot be written to. The only way to clear the bit and re-enable PMD functionality is to perform a device Reset.

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REGISTER 28-2: DEVCFG1: DEVICE CONFIGURATION WORD 1

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	r-1	r-1	r-1	r-1	r-1	r-1	R/P	R/P
	—	—	—	—	—	—	FWDTWINSZ<1:0>	
23:16	R/P	R/P	r-1	R/P	R/P	R/P	R/P	R/P
	FWDTEN	WINDIS	—	WDTPS<4:0>				
15:8	R/P	R/P	R/P	R/P	r-1	R/P	R/P	R/P
	FCKSM<1:0>		FPBDIV<1:0>		—	OSCIOFNC	POSCMOD<1:0>	
7:0	R/P	r-1	R/P	r-1	r-1	R/P	R/P	R/P
	IESO	—	FSOSCEN	—	—	FNOSC<2:0>		

Legend:

R = Readable bit

-n = Value at POR

r = Reserved bit

W = Writable bit

'1' = Bit is set

P = Programmable bit

U = Unimplemented bit, read as '0'

'0' = Bit is cleared

x = Bit is unknown

bit 31-26 **Reserved:** Write '1'

bit 25-24 **FWDTWINSZ<1:0>**: Watchdog Timer Window Size bits

11 = Window size is 25%

10 = Window size is 37.5%

01 = Window size is 50%

00 = Window size is 75%

bit 23 **FWDTEN**: Watchdog Timer Enable bit

1 = Watchdog Timer is enabled and cannot be disabled by software

0 = Watchdog Timer is not enabled; it can be enabled in software

bit 22 **WINDIS**: Watchdog Timer Window Enable bit

1 = Watchdog Timer is in non-Window mode

0 = Watchdog Timer is in Window mode

bit 21 **Reserved:** Write '1'

bit 20-16 **WDTPS<4:0>**: Watchdog Timer Postscale Select bits

10100 = 1:1048576

10011 = 1:524288

10010 = 1:262144

10001 = 1:131072

10000 = 1:65536

01111 = 1:32768

01110 = 1:16384

01101 = 1:8192

01100 = 1:4096

01011 = 1:2048

01010 = 1:1024

01001 = 1:512

01000 = 1:256

00111 = 1:128

00110 = 1:64

00101 = 1:32

00100 = 1:16

00011 = 1:8

00010 = 1:4

00001 = 1:2

00000 = 1:1

All other combinations not shown result in operation = 10100

Note 1: Do not disable the Posc (POSCMOD = 11) when using this oscillator source.

29.0 INSTRUCTION SET

The PIC32MX330/350/370/430/450/470 family instruction set complies with the MIPS32® Release 2 instruction set architecture. The PIC32 device family does not support the following features:

- Core extend instructions
- Coprocessor 1 instructions
- Coprocessor 2 instructions

<p>Note: Refer to “MIPS32® Architecture for Programmers Volume II: The MIPS32® Instruction Set” at www.imgtec.com for more information.</p>
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PIC32MX330/350/370/430/450/470

TABLE 31-37: ANALOG-TO-DIGITAL CONVERSION TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	Symbol	Characteristics	Min.	Typical ⁽¹⁾	Max.	Units	Conditions
Clock Parameters							
AD50	TAD	ADC Clock Period ⁽²⁾	65	—	—	ns	See Table 31-36
Conversion Rate							
AD55	TCONV	Conversion Time	—	12 TAD	—	—	—
AD56	FCNV	Throughput Rate (Sampling Speed) ⁽⁴⁾	—	—	1000	ksps	AVDD = 3.0V to 3.6V
			—	—	400	ksps	AVDD = 2.5V to 3.6V
AD57	TSAMP	Sample Time	2 TAD	—	—	—	—
Timing Parameters							
AD60	TPCS	Conversion Start from Sample Trigger ⁽³⁾	—	1.0 TAD	—	—	Auto-Convert Trigger (SSRC<2:0> = 111) not selected
AD61	TPSS	Sample Start from Setting Sample (SAMP) bit	0.5 TAD	—	1.5 TAD	—	—
AD62	TCSS	Conversion Completion to Sample Start (ASAM = 1) ⁽³⁾	—	0.5 TAD	—	—	—
AD63	TDPU	Time to Stabilize Analog Stage from ADC Off to ADC On ⁽³⁾	—	—	2	μs	—

- Note 1:** These parameters are characterized, but not tested in manufacturing.
2: Because the sample caps will eventually lose charge, clock rates below 10 kHz can affect linearity performance, especially at elevated temperatures.
3: Characterized by design but not tested.
4: Refer to Table 31-36 for detailed conditions.

PIC32MX330/350/370/430/450/470

TABLE 31-41: OTG ELECTRICAL SPECIFICATIONS

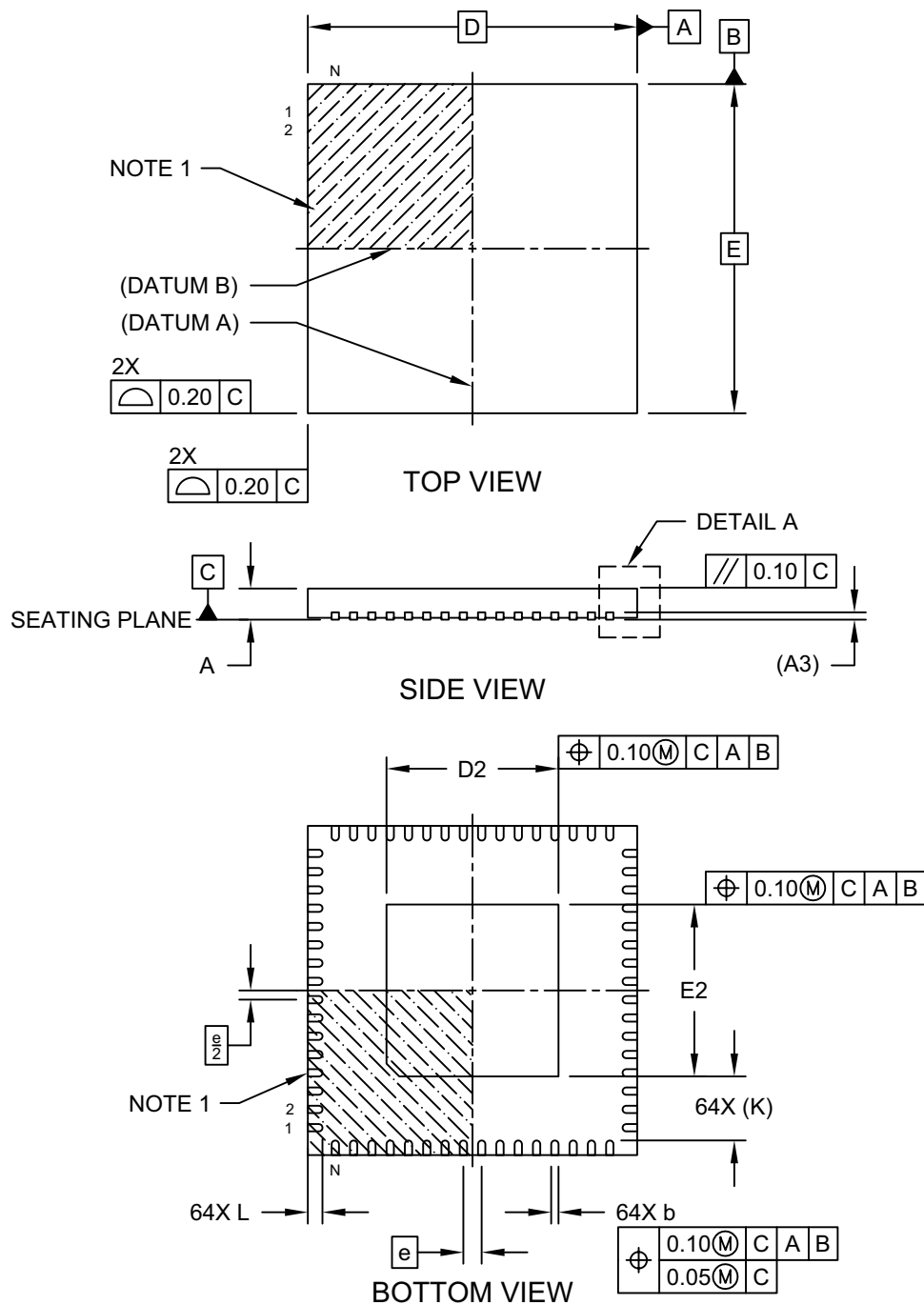
AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	Symbol	Characteristics ⁽¹⁾	Min.	Typ.	Max.	Units	Conditions
USB313	VUSB3V3	USB Voltage	3.0	—	3.6	V	Voltage on VUSB3V3 must be in this range for proper USB operation
USB315	VILUSB	Input Low Voltage for USB Buffer	—	—	0.8	V	—
USB316	VIHUSB	Input High Voltage for USB Buffer	2.0	—	—	V	—
USB318	VDIFS	Differential Input Sensitivity	—	—	0.2	V	The difference between D+ and D- must exceed this value while VCM is met
USB319	VCM	Differential Common Mode Range	0.8	—	2.5	V	—
USB320	ZOUT	Driver Output Impedance	28.0	—	44.0	Ω	—
USB321	VOL	Voltage Output Low	0.0	—	0.3	V	1.425 kΩ load connected to VUSB3V3
USB322	VOH	Voltage Output High	2.8	—	3.6	V	14.25 kΩ load connected to ground

Note 1: These parameters are characterized, but not tested in manufacturing.

PIC32MX330/350/370/430/450/470

64-Terminal Plastic Quad Flat Pack, No Lead (RG) 9x9x0.9 mm Body [QFN] Saw Singulated

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



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